

(19) World Intellectual Property  
Organization  
International Bureau



(43) International Publication Date  
18 March 2004 (18.03.2004)

PCT

(10) International Publication Number  
**WO 2004/022248 A1**

(51) International Patent Classification<sup>7</sup>: **B05D 1/18**,  
1/36, 5/06

Michel A; Beim Franzosengrab 27, St. Inghert, F-66386  
Allemagne (FR).

(21) International Application Number:  
PCT/US2003/027546

(74) Agent: **BEALL, Thomas R**; Corning Incorporated, SP TI  
3 1, Corning, NY 14831 (US).

(22) International Filing Date:  
3 September 2003 (03.09.2003)

(81) Designated States (*national*): AE, AG, AL, AM, AT, AU,  
AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU,  
CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH,  
GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC,  
LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW,  
MX, MZ, NI, NO, NZ, OM, PH, PL, PT, RO, RU, SC, SD,  
SE, SG, SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ,  
VC, VN, YU, ZA, ZM, ZW.

(25) Filing Language: English

(26) Publication Language: English

(84) Designated States (*regional*): European patent (AT, BE,  
BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU,  
IE, IT, LU, MC, NL, PT, SE, SI, SK, TR).

(30) Priority Data:  
0210866 3 September 2002 (03.09.2002) FR

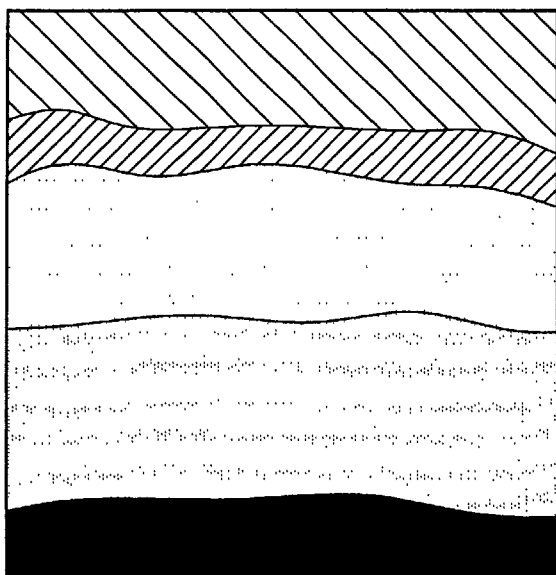
**Published:**  
— with international search report

(71) Applicant: **CORNING INCORPORATED** [US/US]; 1  
Riverfront Plaza, Corning, NY 14831 (US).

For two-letter codes and other abbreviations, refer to the "Guid-  
ance Notes on Codes and Abbreviations" appearing at the begin-  
ning of each regular issue of the PCT Gazette.

(72) Inventors: **GUZMAN, Guillaume**; 56, rue Grande,  
F-77250 Villecerf (FR). **PUTZ, Jorg**; Kantstrasse 34,  
Saarbrücken, F-66125 Allemagne (FR). **AEGERTER,**

(54) Title: A METHOD FOR DEPOSITING A FILM ON A SUBSTRATE



22.1°C  
22  
21  
20  
19  
18  
17  
16  
15  
14.1°C

(57) Abstract: A process for depositing a layer of product on at least part of a major surface of a substrate having two sides separated by a thickness of less than about 3 mm is provided. The process involves using an immersion technique, in which the substrate is placed in a liquid medium containing a solution or dispersion of the product to be deposited or one of its precursors; removed from the liquid medium such that the substrate is coated with a liquid layer, and at least part of the liquid medium contained in the deposited liquid layer is evaporated, wherein the process is characterized as being carried out under conditions in which cooling of the substrate as a result of evaporation of said part of the liquid medium is lim-

WO 2004/022248 A1

ited.